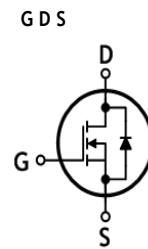
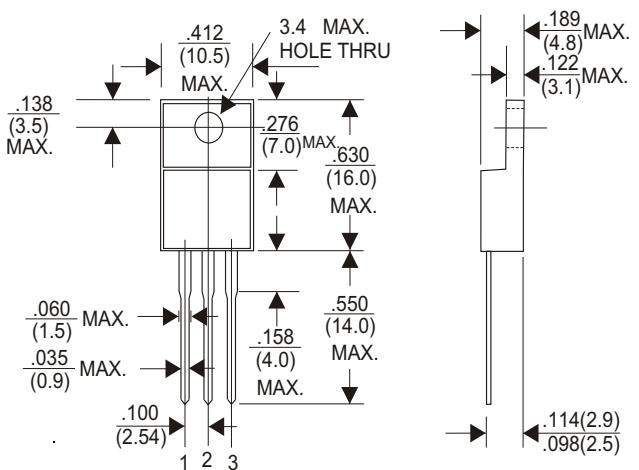


### Features

- Drain-Source voltage:  $V_{DS}=650V$  ( $@T_J=150^{\circ}C$ )
- Low drain-source On resistance:  $R_{DS(on)}=0.38\Omega$  (Max.)
- Ultra low gate charge:  $Q_g=20nC$ (Typ.)
- RoHS compliant device
- 100% avalanche tested



**TO-220F (FULLY INSULATED)**



Dimensions in inches and (millimeters)

### Absolute maximum ratings ( $T_c=25^{\circ}C$ unless otherwise noted)

Characteristic	Symbol	Rating	Unit
Drain-source voltage	$V_{DSS}$	650	V
Gate-source voltage	$V_{GSS}$	$\pm 30$	V
Drain current (DC) (Note 1)	$I_D$	$T_c=25^{\circ}C$	A
		$T_c=100^{\circ}C$	A
Drain current (Pulsed)	$I_{DM}$	44	A
Single pulsed avalanche energy (Note 2)	$E_{AS}$	135	mJ
Repetitive avalanche current (Note 1)	$I_{AR}$	5	A
Repetitive avalanche energy (Note 1)	$E_{AR}$	63.2	mJ
Power dissipation	$P_D$	32	W
Diode dv/dt ruggedness (Note 3)	dv/dt	15	V/ns
MOSFET dv/dt ruggedness (Note 4)	dv/dt	50	V/ns
Junction temperature	$T_J$	150	$^{\circ}C$
Storage temperature range	$T_{stg}$	-55~150	$^{\circ}C$

### Thermal Characteristics

Characteristic	Symbol	Rating	Unit
Thermal resistance, junction to case	$R_{th(j-c)}$	Max. 3.9	$^{\circ}C/W$
Thermal resistance, junction to ambient	$R_{th(j-a)}$	Max. 62.5	$^{\circ}C/W$

# 380R65F

## Electrical Characteristics ( $T_C=25^\circ\text{C}$ unless otherwise noted)

Characteristic	Symbol	Test Condition	Min.	Typ.	Max.	Unit
Drain-source breakdown voltage	$\text{BV}_{\text{DSS}}$	$I_D=250\mu\text{A}, V_{GS}=0$	650	-	-	V
Gate threshold voltage	$V_{GS(\text{th})}$	$I_D=250\mu\text{A}, V_{DS}=V_{GS}$	2	3	4	V
Drain-source cut-off current	$I_{DSS}$	$V_{DS}=650\text{V}, V_{GS}=0\text{V}$	-	-	1	$\mu\text{A}$
		$V_{DS}=650\text{V}, T_J=125^\circ\text{C}$	-	-	100	$\mu\text{A}$
Gate leakage current	$I_{GSS}$	$V_{DS}=0\text{V}, V_{GS}=\pm30\text{V}$	-	-	$\pm100$	nA
Drain-source on-resistance	$R_{DS(\text{ON})}$	$V_{GS}=10\text{V}, I_D=5.5\text{A}$	-	0.31	0.38	$\Omega$
Internal gate resistance	$R_g$	f=1MHz, Open drain	-	21	28	$\Omega$
Input capacitance	$C_{iss}$	$V_{DS}=25\text{V}, V_{GS}=0\text{V}, f=1\text{MHz}$	629	787	945	pF
Output capacitance	$C_{oss}$		344	431	518	
Reverse transfer capacitance	$C_{rss}$		19	24	29	
Turn-on delay time (Note 3)	$t_{d(on)}$	$V_{DS}=350\text{V}, I_D=11\text{A}, R_G=25\Omega$	-	17	25	ns
Rise time (Note 3)	$t_r$		-	14	24	
Turn-off delay time (Note 3)	$t_{d(off)}$		-	40	55	
Fall time (Note 3)	$t_f$		-	5	8	
Total gate charge (Note 4)	$Q_g$	$V_{DS}=400\text{V}, V_{GS}=10\text{V}, I_D=7\text{A}$	-	20	25	nC
Gate-source charge (Note 4)	$Q_{gs}$		-	6.5	10	
Gate-drain charge (Note 4)	$Q_{gd}$		-	5	10	

## Source-Drain Diode Ratings and Characteristics ( $T_C=25^\circ\text{C}$ unless otherwise noted)

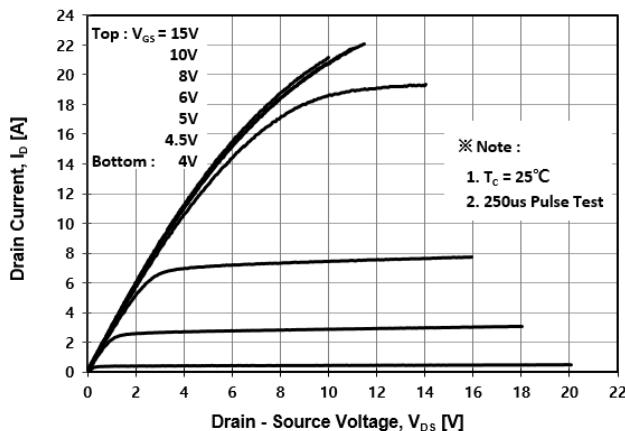
Characteristic	Symbol	Test Condition	Min.	Typ.	Max.	Unit
Source current (DC)	$I_S$	Integral reverse diode in the MOSFET	-	-	11	A
Source current (Pulsed)	$I_{SM}$		-	-	44	A
Forward voltage	$V_{SD}$	$V_{GS}=0\text{V}, I_S=11\text{A}$	-	-	1.2	V
Reverse recovery time (Note 3,4)	$t_{rr}$	$I_S=11\text{A}, V_{GS}=0\text{V}, dI_S/dt=100\text{A}/\mu\text{s}$	-	326	450	ns
Reverse recovery charge (Note 3,4)	$Q_{rr}$		-	2.8	4.5	$\mu\text{C}$

Note:

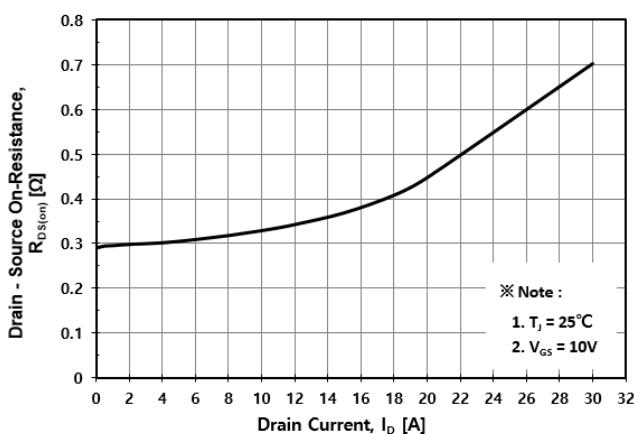
1. Calculated continuous current based on maximum allowable junction temperature
2. L=10mH,  $I_{AS}=5\text{A}$ ,  $V_{DD}=50\text{V}$ , Starting  $T_J=25^\circ\text{C}$
3. Guaranteed by design, not subject to production testing
4. Pulse test: Pulse width $\leq300\text{us}$ , Duty cycle $\leq2\%$

## RATING AND CHARACTERISTIC CURVES (380R65F)

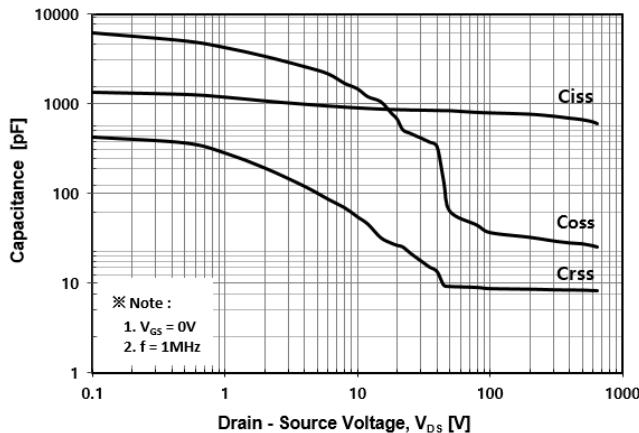
**Fig. 1 Typical Output Characteristics**



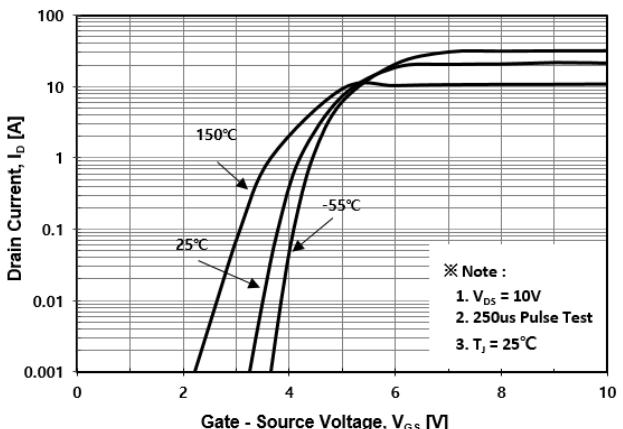
**Fig.3 On-Resistance Variation with Drain Current and Gate Voltage**



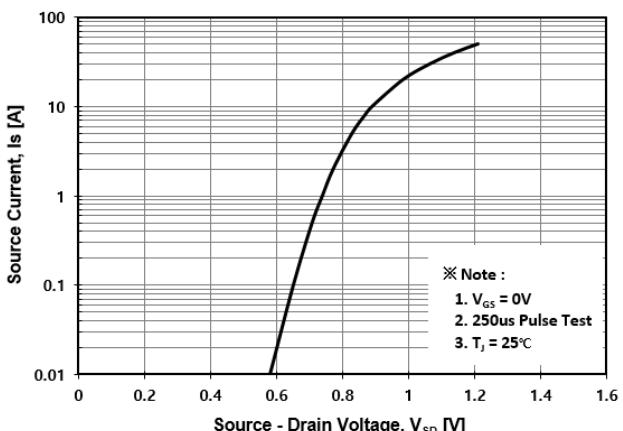
**Fig. 5 Typical Capacitance Characteristics**



**Fig. 2 Typical Transfer Characteristics**

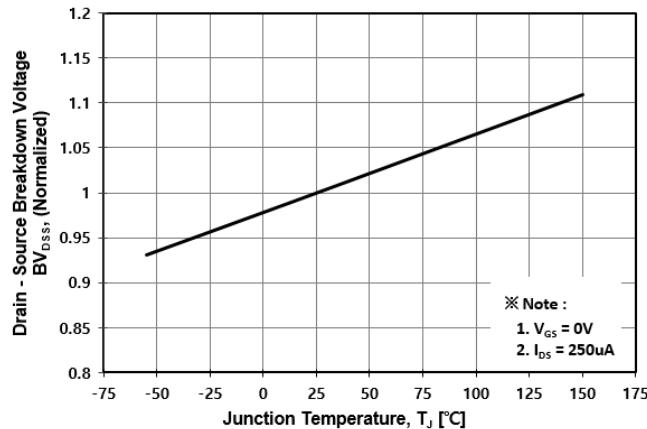


**Fig. 4 Body Diode Forward Voltage Variation with Source Current**

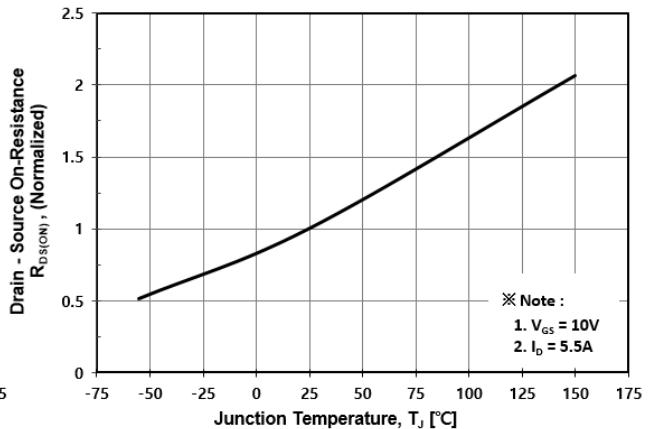


## RATING AND CHARACTERISTIC CURVES (380R65F)

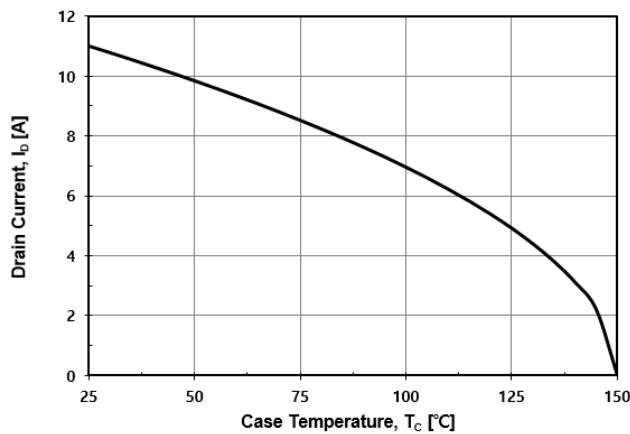
**Fig. 7 Breakdown Voltage Variation vs. Temperature**



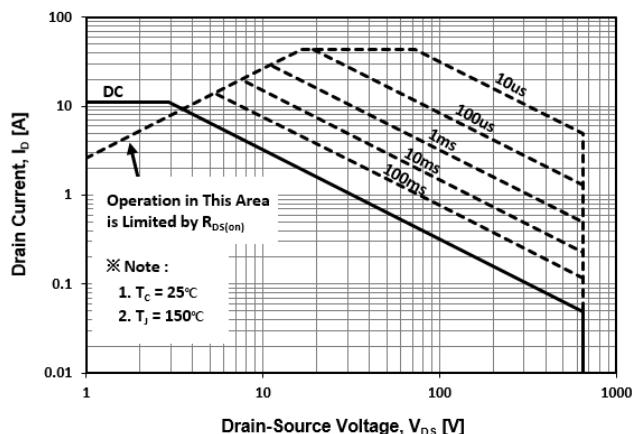
**Fig. 8 On-Resistance Variation vs. Temperature**



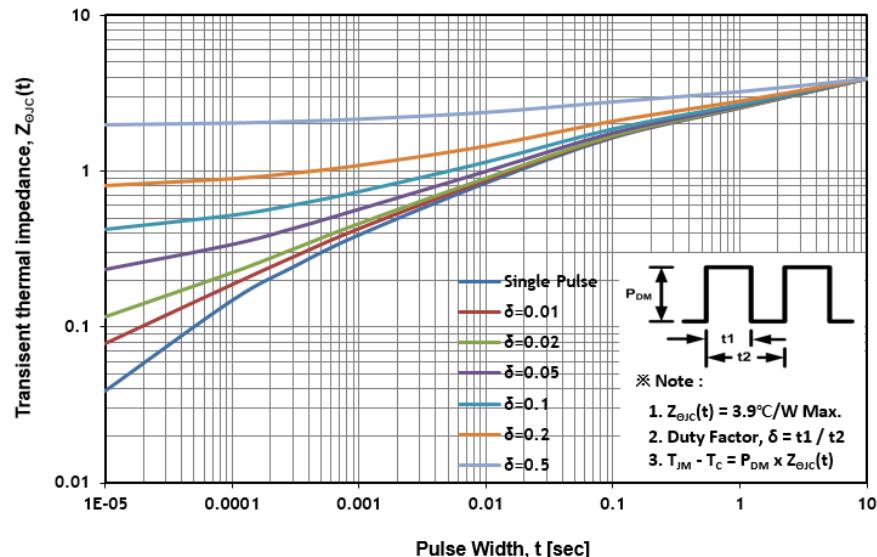
**Fig. 9 Maximum Drain Current vs. Case Temperature**



**Fig. 10 Maximum Safe Operating Area**



**Fig. 11 Transient Thermal Impedance**



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